### Materials Declaration

#### Molding Compound

<table>
<thead>
<tr>
<th>Description</th>
<th>Substance</th>
<th>CAS#</th>
<th>Weight (g)</th>
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<tbody>
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#### Leadframe

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#### Internal/External Leadframe Plating

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| Package Totals | | | 6.83E-03 | 100 | 1000000 |

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.
## Product / Package Information
- **Package**: SC70 - Isolated Backside
- **Body Size**: Proprietary
- **Lead Count**: 3
- **Terminal Finish**: 100 Sn
- **MS Number**: MS011467A

## Environmental Compliance Information
- **RoHS Compliant**: Yes
- **High Temperature Compliant**: Yes
- **Halogen Free Compliant**: Yes
- **REACH SVHC Compliant**: Yes

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### Bond Wires

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ADI Proprietary
### Materials Declaration

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<tr>
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#### Leadframe

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#### Bond Wires

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#### Chip

<table>
<thead>
<tr>
<th>Description</th>
<th>Substance</th>
<th>CAS#</th>
<th>Weight (g)</th>
<th>Percentage (%)</th>
<th>PPM</th>
<th>Homogeneous Material Level</th>
<th>Component Level</th>
</tr>
</thead>
<tbody>
<tr>
<td>Other inorganic materials</td>
<td>Linput lead</td>
<td>1440-21-3</td>
<td>2.14 E-04</td>
<td>100</td>
<td>1000000</td>
<td>0.54</td>
<td>541220</td>
</tr>
</tbody>
</table>

#### Die Attach

<table>
<thead>
<tr>
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<th>Component Level</th>
</tr>
</thead>
<tbody>
<tr>
<td>Other inorganic materials</td>
<td>Silicon dioxide</td>
<td>14808-31-7</td>
<td>1.50 E-05</td>
<td>50.00</td>
<td>50000</td>
<td>0.27</td>
<td>274190</td>
</tr>
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</table>

#### Package Totals

<table>
<thead>
<tr>
<th></th>
<th>Weight (g)</th>
<th>Percentage (%)</th>
<th>PPM</th>
</tr>
</thead>
<tbody>
<tr>
<td>Package</td>
<td>5.48 E-03</td>
<td>100</td>
<td>1000000</td>
</tr>
</tbody>
</table>

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.